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(12) **United States Design Patent**
Liao et al.

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(45) **Date of Patent: ** Sep. 9, 2008**

(54) **LINEAR MODULE**

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(73) Assignee: **Hiwin Mikrosystem Corp.**, Taichung (TW)

(**) Term: **14 Years**

(21) Appl. No.: **29/286,636**

(22) Filed: **May 14, 2007**

(51) **LOC (8) Cl.** **15-09**
(52) **U.S. Cl.** **D15/143**
(58) **Field of Classification Search** D13/158, D13/162, 184; D15/1–5, 7, 9, 143, 148, D15/149, 199; 29/56; 60/412; 74/89.15, 74/490.09; 192/141; 310/10, 12, 15, 20, 310/80, 178, 317, 319
See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a linear module, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of a linear module showing our new design thereof;

FIG. **2** is a front elevational view thereof;

FIG. **3** is a rear elevational view thereof;

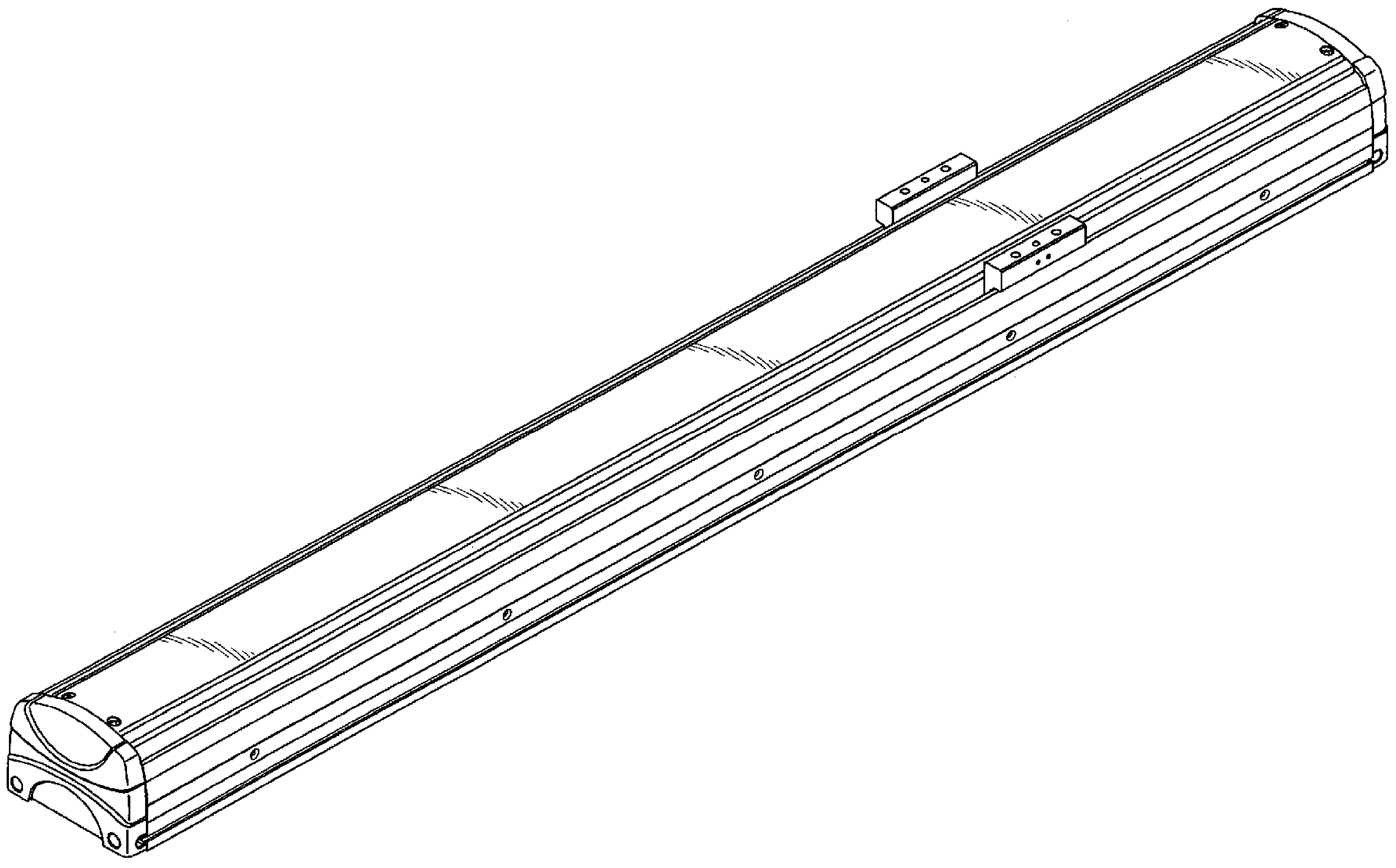
FIG. **4** is a left side elevational view thereof;

FIG. **5** is a right side elevational view thereof;

FIG. **6** is a top plan view thereof; and,

FIG. **7** is a bottom plan view thereof.

1 Claim, 4 Drawing Sheets



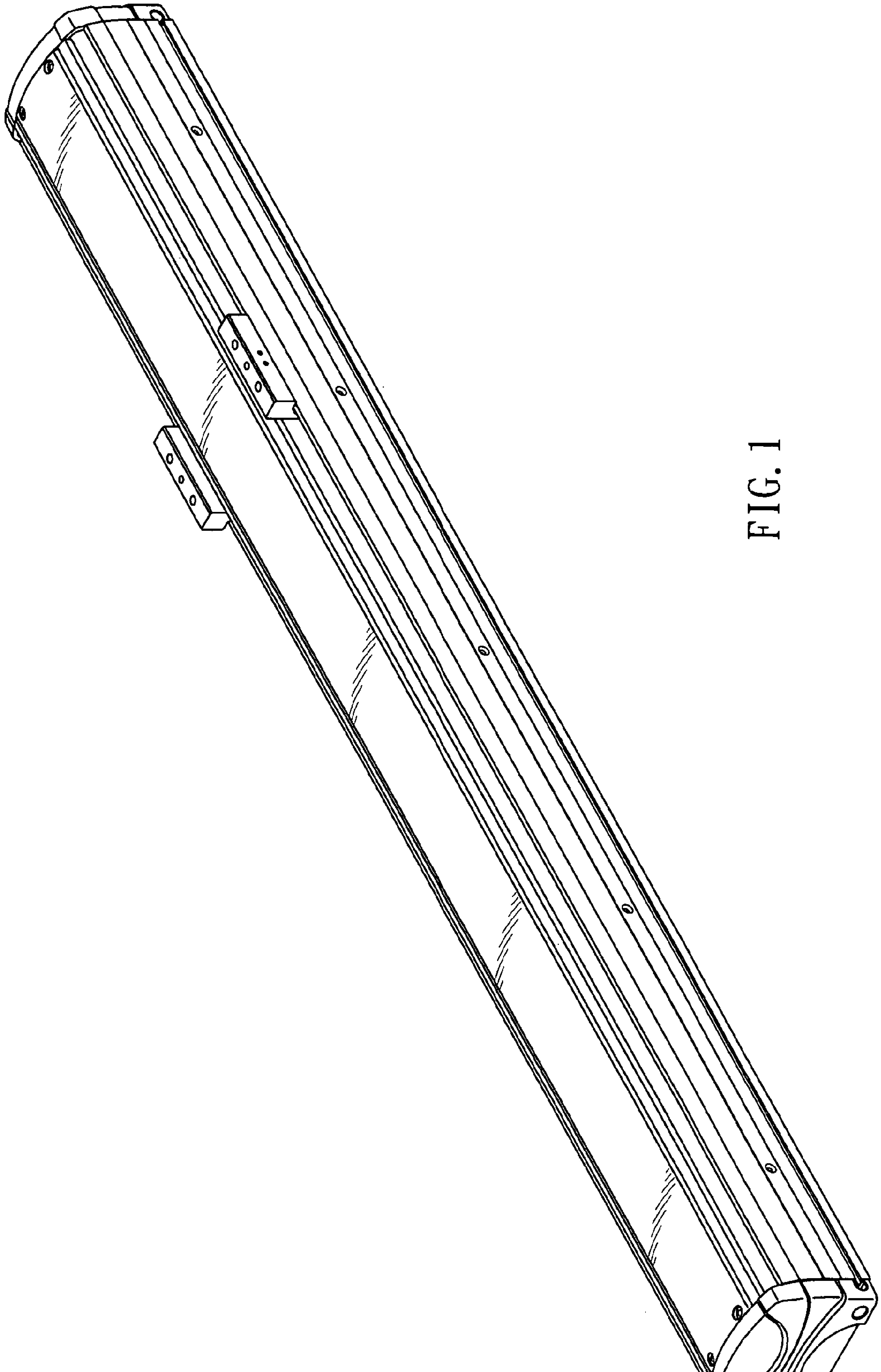


FIG. 1

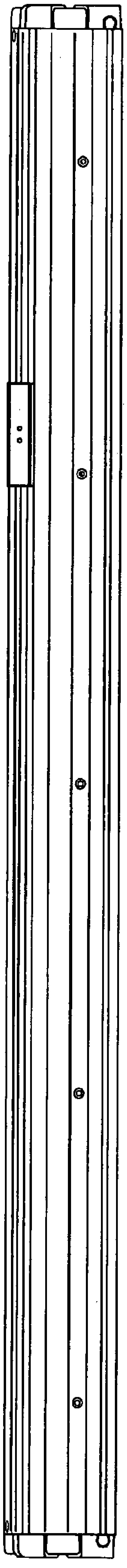


FIG. 2

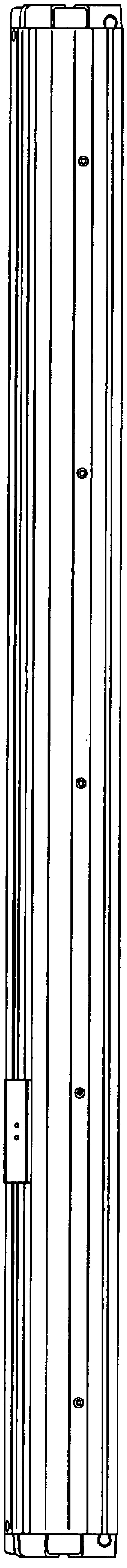


FIG. 3

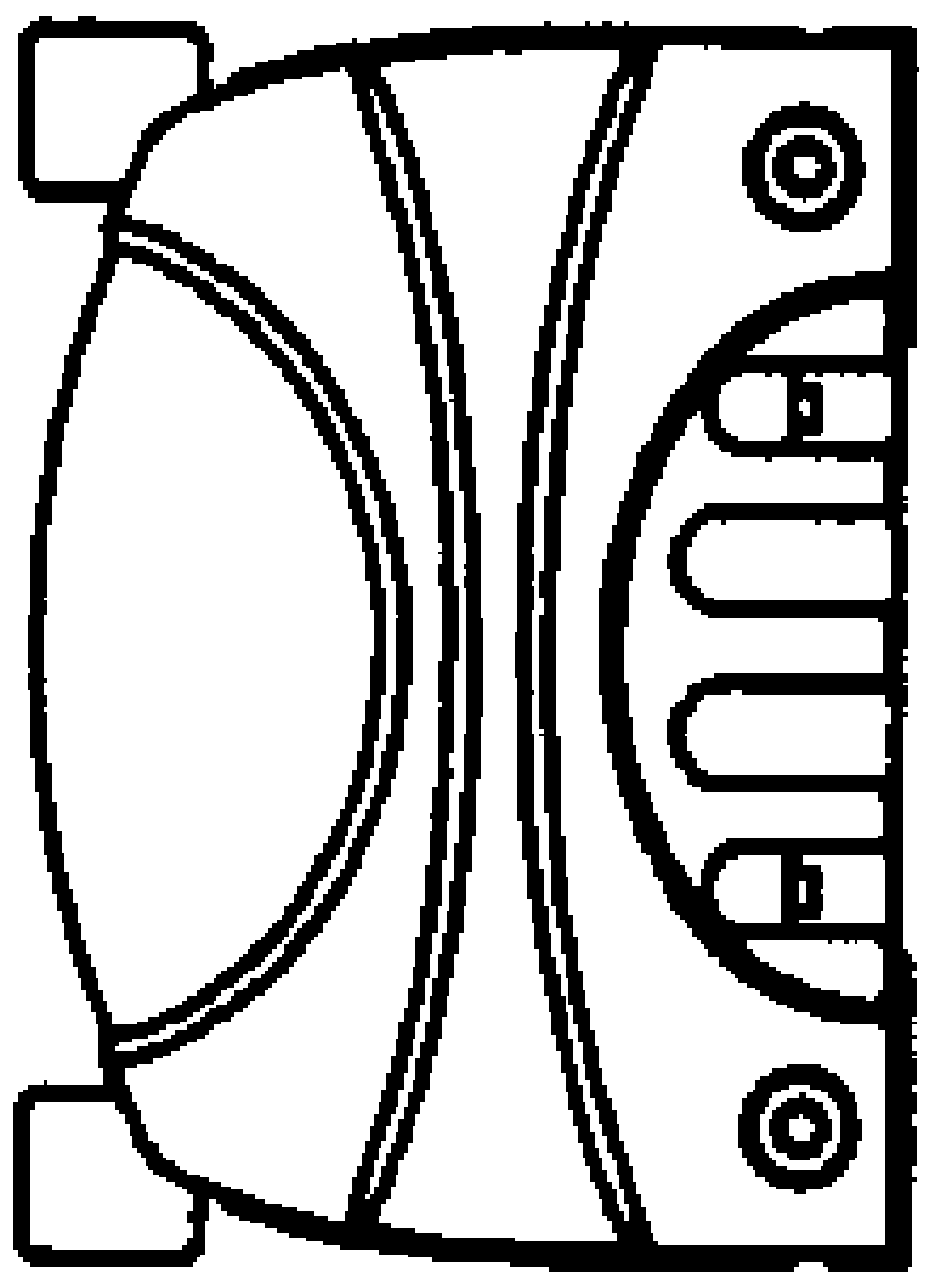


FIG. 5

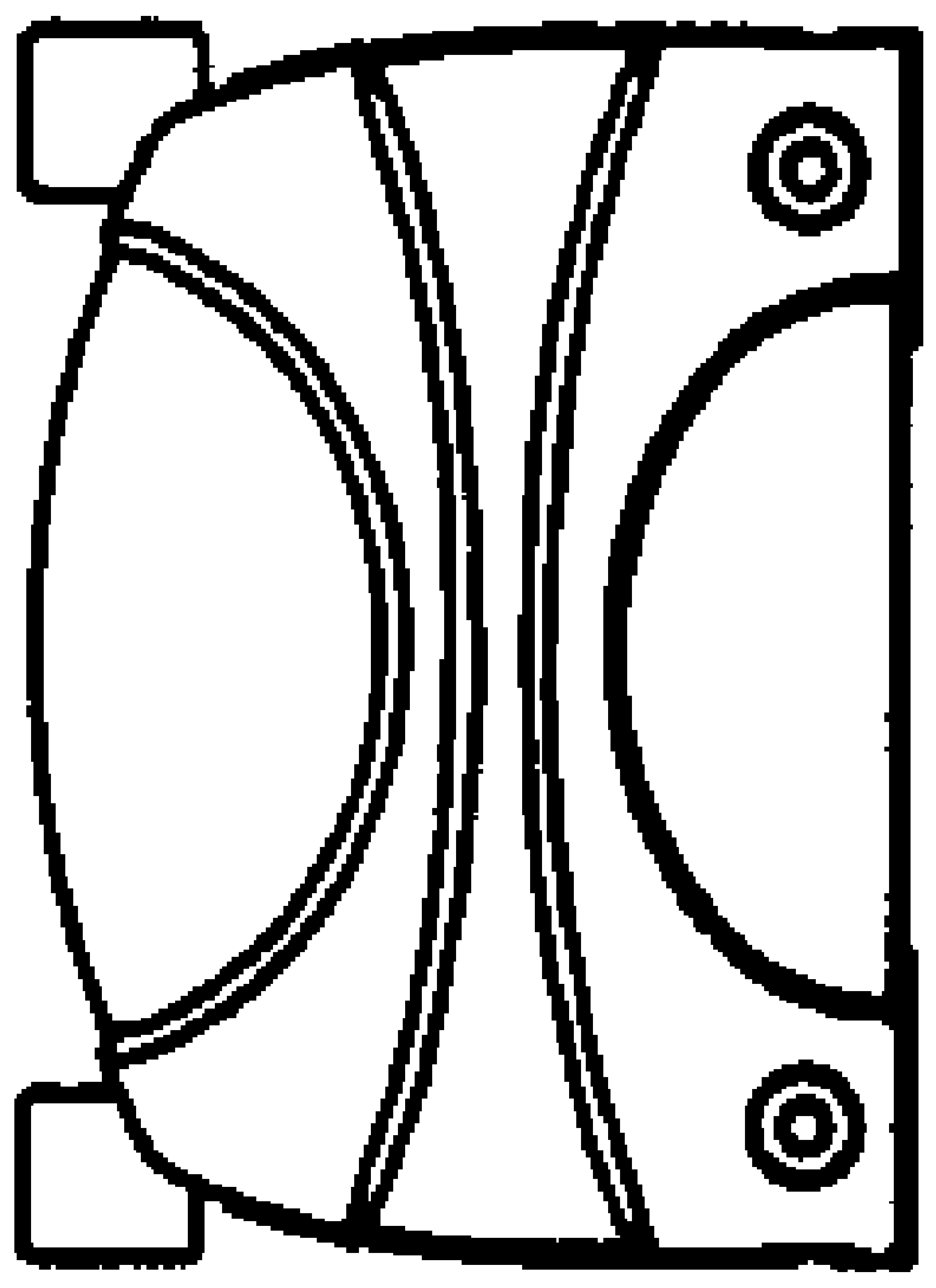


FIG. 4

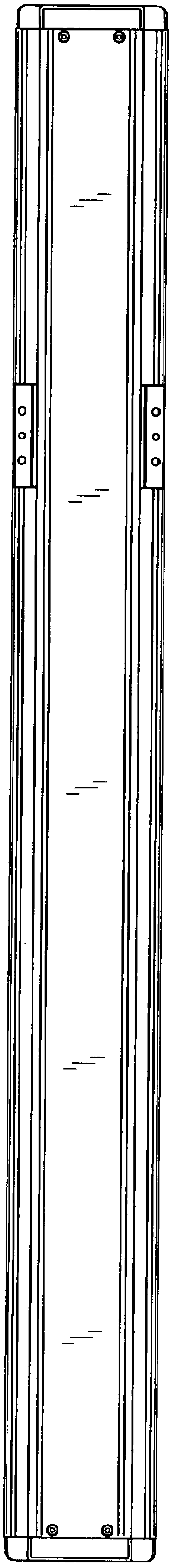


FIG. 6

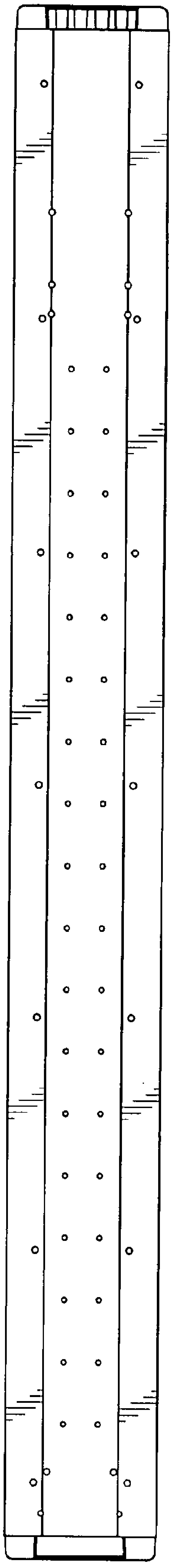


FIG. 7